



## **SPECIFICATION**

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N : CL31C101JCCNFNC
- Description : CAP, 100pF, 100V, ±5%, C0G, 1206

A. Samsung Part Number

|            |               |                                       | <u>CL</u> 31<br>①② | <u>C</u><br>3 | <u>101</u><br>④ | <u>J</u><br>(5) | <u>C</u><br>6 | <u>C</u><br>⑦ | <u>N</u><br>8 | <u>F</u><br>9 | <u>N</u><br>10 | <u>C</u><br>ໜ |                   |
|------------|---------------|---------------------------------------|--------------------|---------------|-----------------|-----------------|---------------|---------------|---------------|---------------|----------------|---------------|-------------------|
| 1          | Series        | Samsung Multi-layer Ceramic Capacitor |                    |               |                 |                 |               |               |               |               |                |               |                   |
| 2          | Size          | 1206 (in                              | ch code)           |               | L:              | 3.2             | ± 0.1         | 5             | mm            |               | W:             | 1.6 ± 0.1     | 15 mm             |
| 3          | Dielectric    | C0G                                   |                    |               |                 | 8               | Inne          | r ele         | ctroc         | le            |                | Ni            |                   |
| 4          | Capacitance   | <b>100</b> pF                         |                    |               |                 |                 | Tern          | ninat         | ion           |               |                | Cu            |                   |
| 5          | Capacitance   | ±5 %                                  |                    |               |                 |                 | Plati         | ng            |               |               |                | Sn 100%       | (Pb Free)         |
|            | tolerance     |                                       |                    |               |                 | 9               | Proc          | luct          |               |               |                | Product for   | POWER application |
| 6          | Rated Voltage | 100 V                                 |                    |               |                 | 10              | Spee          | cial          |               |               |                | Reserved for  | or future use     |
| $\bigcirc$ | Thickness     | 0.85 ± 0                              | ).15 mm            |               |                 | 1               | Pack          | kagir         | ng            |               |                | Cardboard     | Type, 7" reel     |

## B. Samsung Reliablility Test and Judgement condition

|                   | Performance  | Test condition                                   |  |  |  |  |  |  |
|-------------------|--|--|--|--|--|--|--|--|
| Capacitance       | Within specified tolerance                                       | 1M±±10% 0.5~5Vrms                                |  |  |  |  |  |  |
| Q                 | 1000 min   |  |  |  |  |  |  |  |
| Insulation        | 10,000Mohm or 500Mohm⋅ <i>μ</i> F                                | Rated Voltage 60~120 sec.                        |  |  |  |  |  |  |
| Resistance        | Whichever is Smaller   |  |  |  |  |  |  |  |
| Appearance        | No abnormal exterior appearance                                  | Microscope (×10)                                 |  |  |  |  |  |  |
| Withstanding      | No dielectric breakdown or                                       | 200% of the rated voltage                        |  |  |  |  |  |  |
| Voltage           | mechanical breakdown   |  |  |  |  |  |  |  |
| Temperature       | C0G  |  |  |  |  |  |  |  |
| Characterisitcs   | (From -55℃ to 125℃, Capacitance change shoud be within ±30PPM/℃) |  |  |  |  |  |  |  |
| Adhesive Strength | No peeling shall be occur on the                                 | 500g·F, for 10±1 sec.                            |  |  |  |  |  |  |
| of Termination    | terminal electrode   |  |  |  |  |  |  |  |
| Bending Strength  | Capacitance change :   | Bending to the limit (1mm)                       |  |  |  |  |  |  |
|                   | within $\pm 5\%$ or $\pm 0.5$ pF whichever is larger             | with 1.0mm/sec.                                  |  |  |  |  |  |  |
| Solderability     | More than 75% of terminal surface                                | SnAg3.0Cu0.5 solder                              |  |  |  |  |  |  |
|                   | is to be soldered newly  | 245±5℃, 3±0.3sec.                                |  |  |  |  |  |  |
|                   |  | (preheating : 80~120 $^{\circ}$ C for 10~30sec.) |  |  |  |  |  |  |
|                   |  |  |  |  |  |  |  |  |
| Resistance to     | Capacitance change :   | Solder pot : 270±5℃, 10±1sec.                    |  |  |  |  |  |  |
| Soldering heat    | within $\pm 2.5\%$ or $\pm 0.25$ pF whichever is larger          |  |  |  |  |  |  |  |
|                   | Tan δ, IR : initial spec.  |  |  |  |  |  |  |  |

|                  | Performance   | Test condition   |  |  |  |  |  |
|------------------|---|--|--|--|--|--|--|
| Vibration Test   | Capacitance change :                                    | Amplitude : 1.5mm  |  |  |  |  |  |
|                  | within ±2.5% or ±0.25pF whichever is larger             | From 10Hz to 55Hz (return : 1min.)                           |  |  |  |  |  |
|                  | Tan δ, IR : initial spec.                               | 2hours $\times$ 3 direction (x, y, z)                        |  |  |  |  |  |
| Moisture         | Capacitance change :                                    | With rated voltage   |  |  |  |  |  |
| Resistance       | within $\pm 7.5\%$ or $\pm 0.75$ pF whichever is larger | 40±2℃, 90~95%RH, 500+12/-0hrs                                |  |  |  |  |  |
|                  | Q : 200 min   |  |  |  |  |  |  |
|                  | IR : 500Mohm or 25Mohm $\cdot \mu F$                    |  |  |  |  |  |  |
|                  | Whichever is Smaller                                    |  |  |  |  |  |  |
| High Temperature | Capacitance change :                                    | With 200% of the rated voltage                               |  |  |  |  |  |
| Resistance       | within $\pm 3\%$ or $\pm 0.3$ pF whichever is larger    | Max. operating temperature                                   |  |  |  |  |  |
|                  | Q : 350 min   | 1000+48/-0hrs  |  |  |  |  |  |
|                  | IR : 1000Mohm or 50Mohm · μF                            |  |  |  |  |  |  |
|                  | Whichever is Smaller                                    |  |  |  |  |  |  |
| Temperature      | Capacitance change :                                    | 1 cycle condition  |  |  |  |  |  |
| Cycling          | within $\pm 2.5\%$ or $\pm 0.25$ pF whichever is larger | Min. operating temperature $\rightarrow$ 25 °C               |  |  |  |  |  |
|                  | Tan δ, IR : initial spec.                               | $\rightarrow$ Max. operating temperature $\rightarrow$ 25 °C |  |  |  |  |  |
|                  |   |  |  |  |  |  |  |
|                  |   |  |  |  |  |  |  |
|                  |   | 5 cycle test   |  |  |  |  |  |

## C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5°C, 10sec. Max )

\* For the more detail Specification, Please refer to the Samsung MLCC catalogue.